

# SOT317-3

plastic quad flat package; 100 leads (lead length 1.95 mm);  
body 14 x 20 x 2.8 mm

8 February 2016

Package information

## 1. Package summary

<b>Terminal position code</b>	Q (quad)
<b>Package type descriptive code</b>	QFP100
<b>Package type industry code</b>	QFP100
<b>Package style descriptive code</b>	QFP (quad flat package)
<b>Package style suffix code</b>	NA (not applicable)
<b>Package body material type</b>	P (plastic)
<b>JEDEC package outline code</b>	MO-112
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	25-2-2003

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	19.9	-	20	20.1	mm
E	package width	13.9	-	14	14.1	mm
A	seated height	[tbd]	-	3.4	3.4	mm
A <sub>2</sub>	package height	2.65	-	2.8	2.9	mm
n <sub>2</sub>	actual quantity of termination	-	-	100	-	

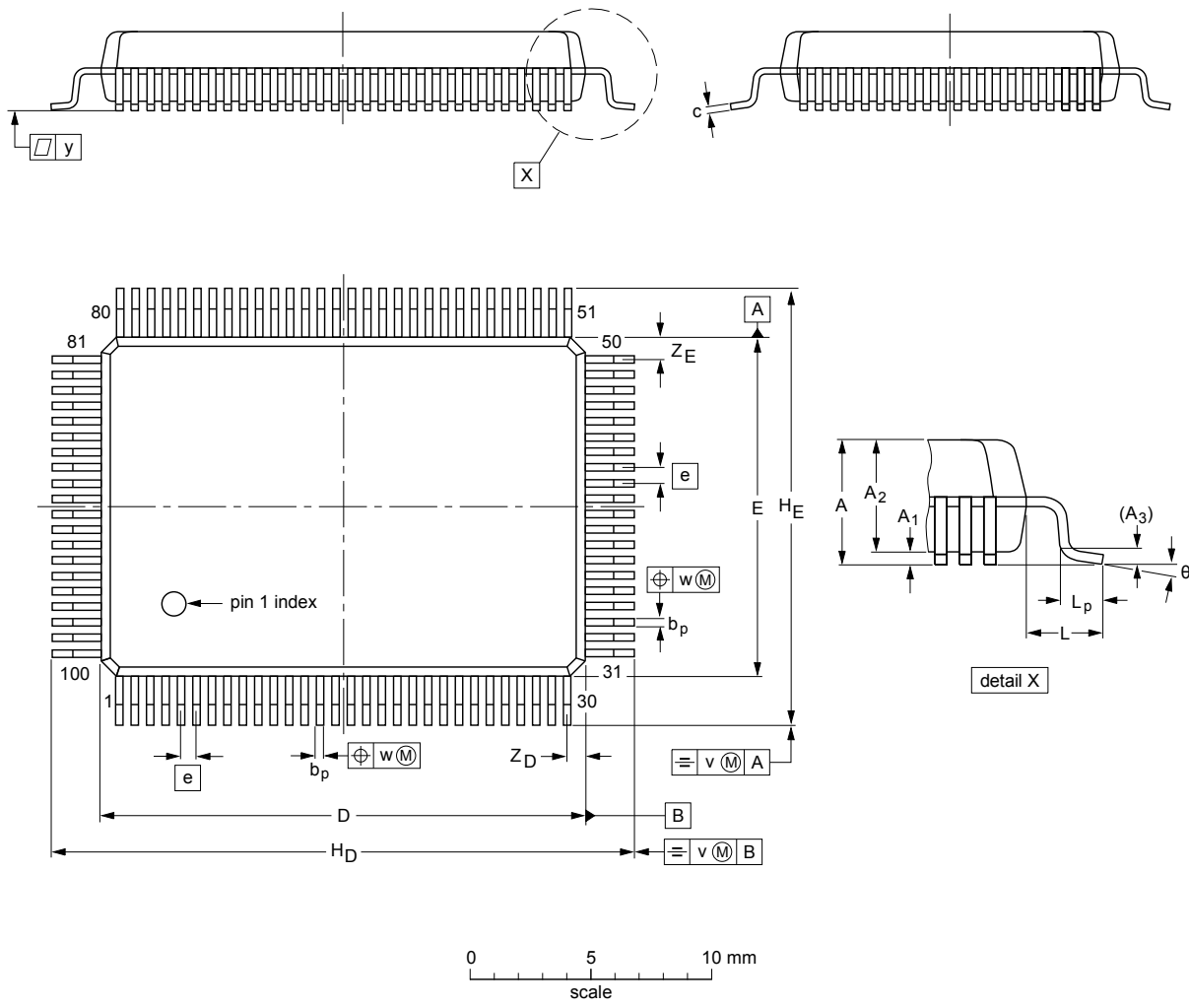


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## 2. Package outline

QFP100: plastic quad flat package; 100 leads (lead length 1.95 mm); body 14 x 20 x 2.8 mm

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**DIMENSIONS (mm are the original dimensions)**

UNIT	A max.	A <sub>1</sub>	A <sub>2</sub>	A <sub>3</sub>	b <sub>p</sub>	c	D <sup>(1)</sup>	E <sup>(1)</sup>	e	H <sub>D</sub>	H <sub>E</sub>	L	L <sub>p</sub>	v	w	y	Z <sub>D</sub> <sup>(1)</sup>	Z <sub>E</sub> <sup>(1)</sup>	θ
mm	3.4	0.45 0.25	2.90 2.65	0.25	0.40 0.25	0.25 0.14	20.1 19.9	14.1 13.9	0.65	24.2 23.6	18.2 17.6	1.95	1.0 0.73	0.2	0.15	0.1	0.8 0.4	1.0 0.6	7° 0°

**Note**

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT317-3		MO-112				99-12-15 03-02-25

Fig. 1. Package outline QFP100 (SOT317-3)

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### 3. Soldering

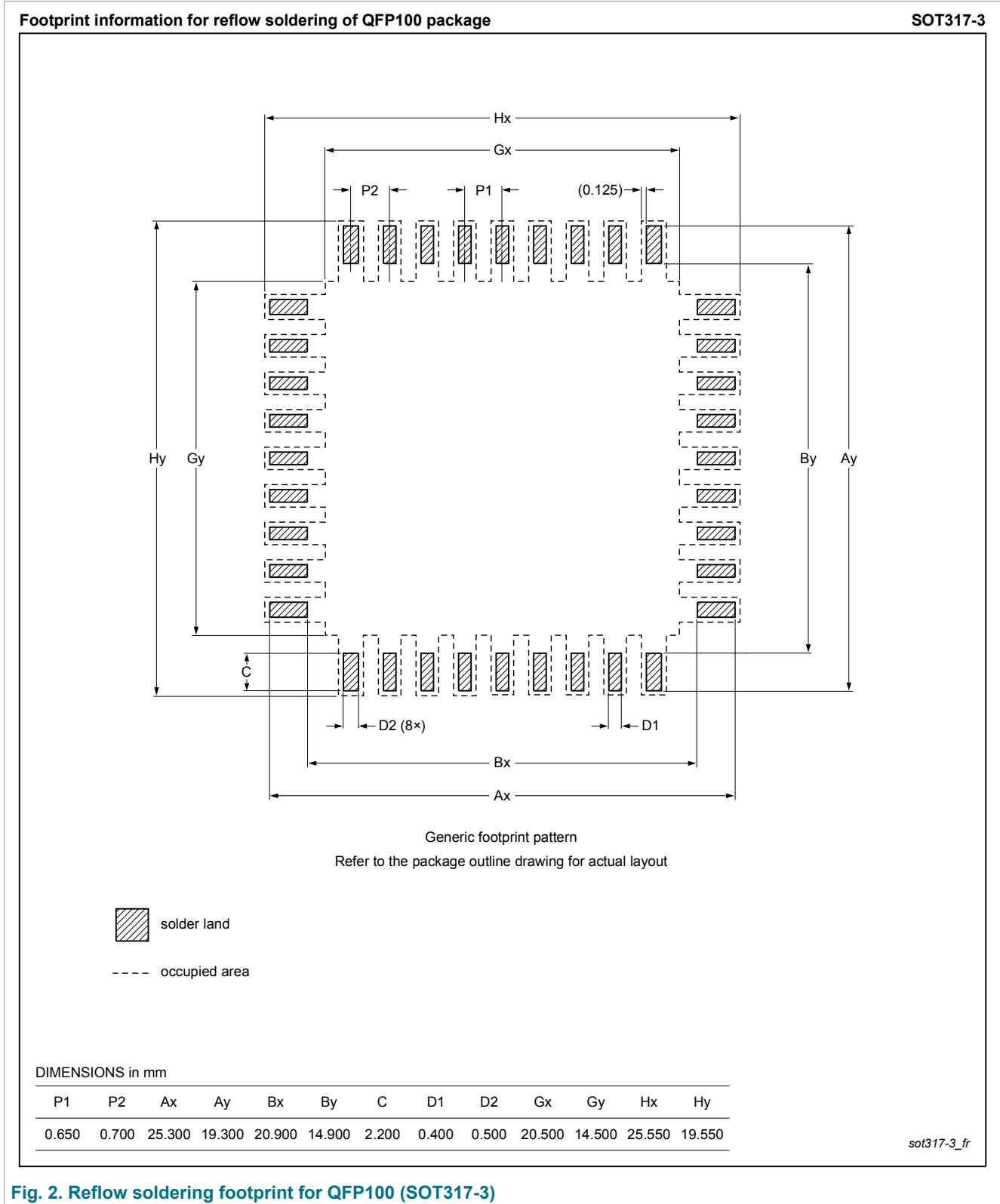


Fig. 2. Reflow soldering footprint for QFP100 (SOT317-3)

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## 4. Legal information

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